

Title (en)

ELECTRONIC COMPONENT AND ELECTRONIC DEVICE COMPRISING SAME

Title (de)

ELEKTRONISCHE KOMPONENTE UND ELEKTRONISCHE VORRICHTUNG DAMIT

Title (fr)

COMPOSANT ÉLECTRONIQUE, ET DISPOSITIF ÉLECTRONIQUE LE COMPRENANT

Publication

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Application

EP 17846801 A 20170613

Priority

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Abstract (en)

[origin: EP3509278A1] An electronic component (and/or an electronic device comprising the same) according to various embodiments of the present invention comprises: a substrate having a sensing element mounted on one surface thereof; a flexible printed circuit board that is coupled to the other surface of the substrate so as to face the same and extends to a side of the substrate along a first direction; and at least one recess formed on the edge of the other surface of the substrate, wherein the recess is located in an area, on the other surface of the substrate, which faces at least the flexible printed circuit board, and may extend along a second direction intersecting with the first direction. The electronic component and/or the electronic device comprising the same as described above may be diversified according to embodiments.

IPC 8 full level

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